LASER X

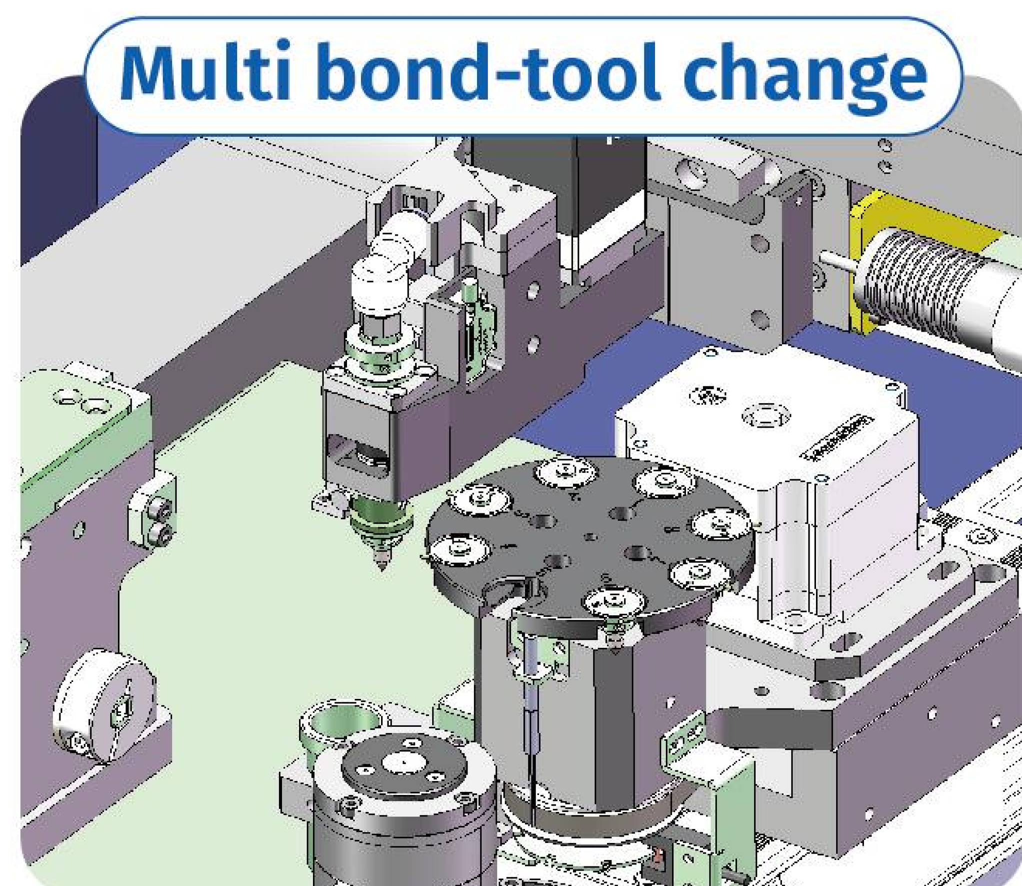
DB-150A

High Precision Multi-chip Die Bonder

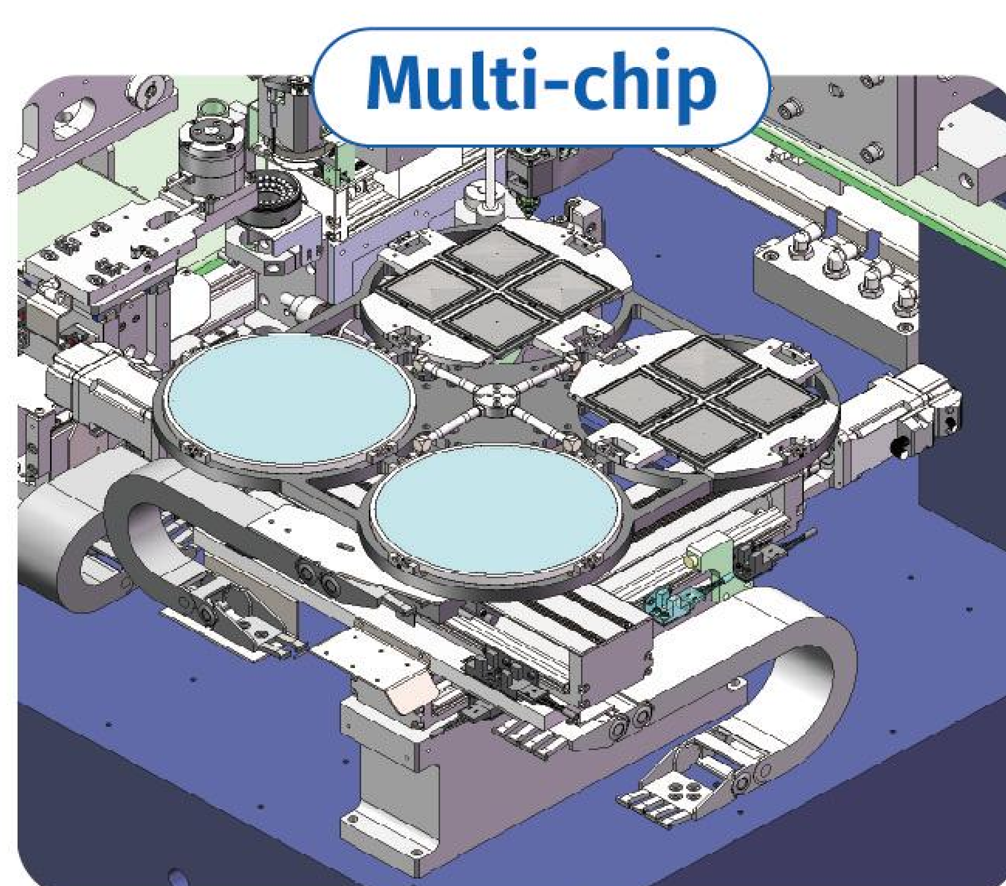
Features

- Multi-chip bonding capability
  -Auto bond-tool change, up to 4 bond-tool buffers
  -Auto wafer change, up to 4 x 6” wafer ring
  -Optional: Waffle pack, Gel-Pak, tray or by request
- Achieving ±3μm XY placement accuracy
- Supports epoxy stamping and dispensing
- Automatic material handling system

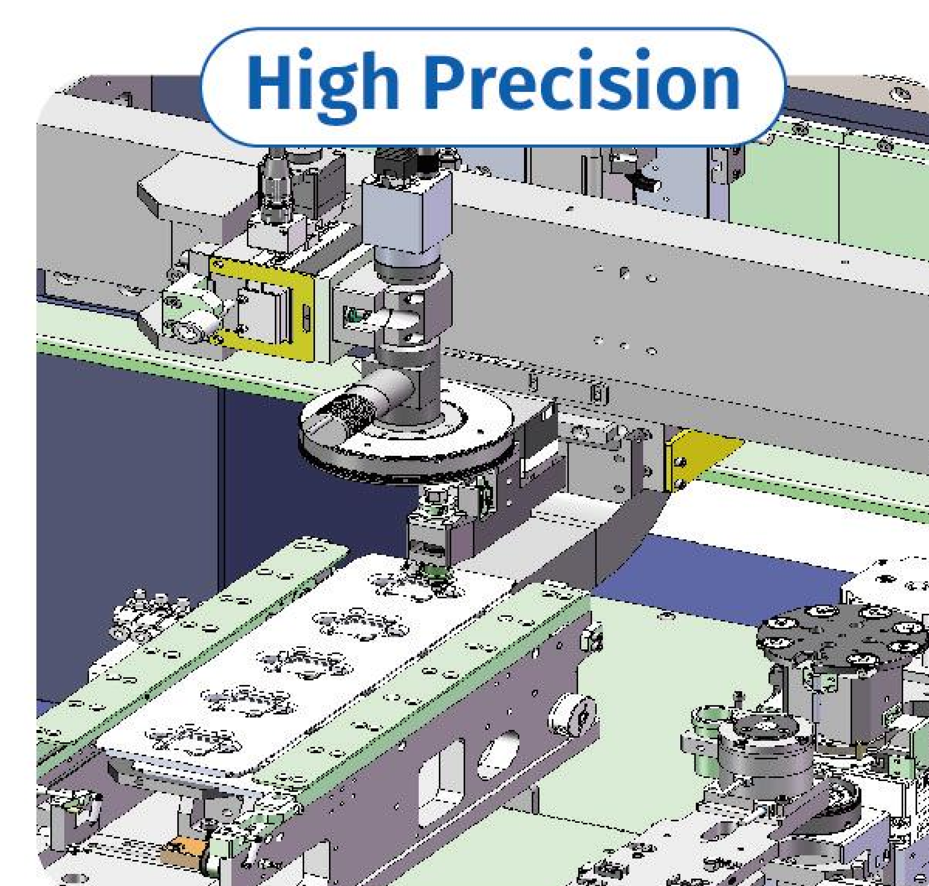
Multi bond-tool change



Multi-chip



High Precision



Specifications

No.	Description	Parameter
01	XY Placement accuracy	±5um @3 sigma ±3um (Standard chip)
02	Die rotation accuracy	±0.3° @3 sigma
03	Bonding force	10gf~200gf (Programmable)
04	Cycle time	≤ 6 s
05	Epoxy system	Stamping or Dispensing
06	Ejector system	1 set
07	Wafer ring	4*6 inch
08	Optics system	3 set Aligning cameras + 1 set Uplook camera
09	Die size	Min:0.12mm*0.12mm / Max:5mm*5mm
10	Substrate size	Width:50~100 mm / Length:50~200 mm
11	Magazines	2 pcs
12	Power Supply	200-240VAC, 50-60Hz, 3000W
13	Pneumatic	CDA:0.5~0.6Mpa / VACUUM:-60~-80KPa
14	Dimensions	1240(L)x1160(W)x1830mm(H)
15	Weight	1200kg

LASER X

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